



optoelectronics

玲涛光电

SPECIFICATION

LT P/N

LT3006WH-A-GL

R&D

Mass Product



Contents

1. Description

1.1 General Description

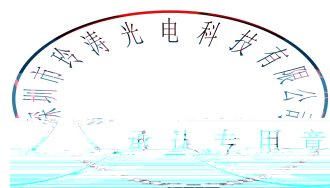
1.2 Features

1.3 Application

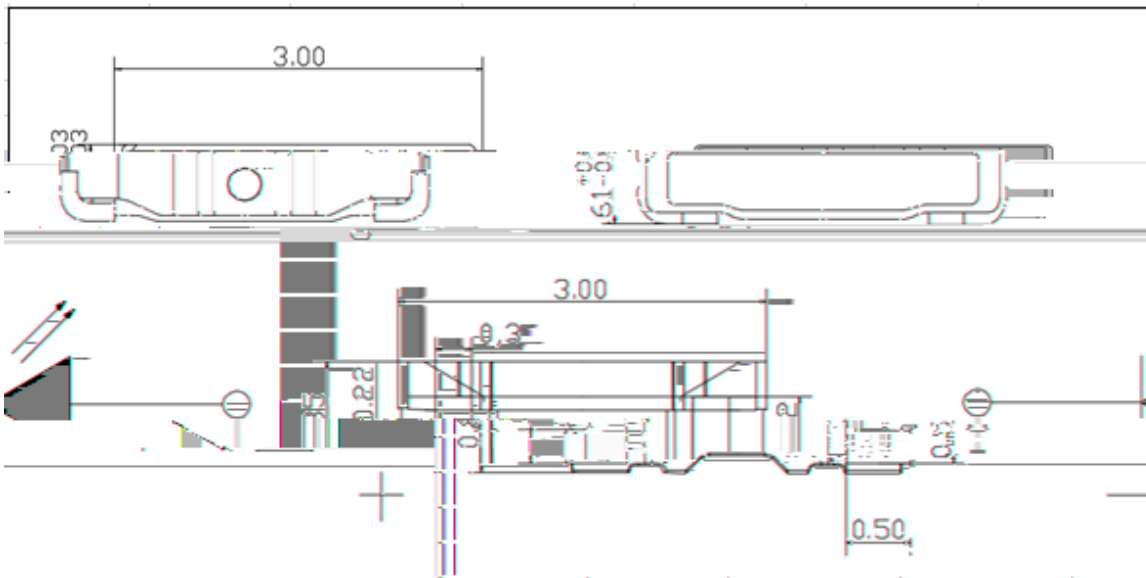
1.4 Package Dimension

1.5 Product Parameters

1.6 Bin Range OR F6 12 Tf374.35 Tm434<</MCID(IF=37)>> BDC



1.4 Package Dimension



Notes

1. All dimensions units are millimeters.
2. All dimensions tolerances are $\pm 0.1\text{mm}$ unless otherwise noted. ± 0.1

1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at $T_s=25^\circ\text{C}$

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	V_F	$I_F=20\text{mA}$	---	3.0	---	V
Reverse Current	I_R	$V_R=5\text{V}$	---	---	1	μA
Luminous	I_v	$I_F=20\text{mA}$	---	2850	---	mcd
Viewing Angle		$I_F=20\text{mA}$	---	120	---	deg

Table 1-2 Absolute Maximum Ratings at Ts=25°C

Parameter	Symbol	Rating	Units
Forward Current	I _F	30	mA
Peak Forward Current	I _{FP}	100	mA
Reverse Voltage	V _R	5	V
Electrostatic Discharge (HBM)	E _{SD}	2000	V
LED Junction Temperature (LED结温)	T _j	105	°C
Operating Temperature	T _{OPR}	-30 ~ + 85	°C
Storage Temperature	T _{STG}	-40~100	°C

Notes

- 1/10 Duty cycle, 0.1ms pulse width. 0.1ms, 1/10.
- The above forward voltage measurement allowance tolerance is $\pm 0.03V$. $\pm 0.03V$.
- The above color coordinates measurement allowance tolerance is ± 0.003 . ± 0.003 .
- The above luminous intensity measurement allowance tolerance $\pm 3\%$. $\pm 3\%$.
- Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
- All measurements were made under the standardized environment of LT.
- When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED

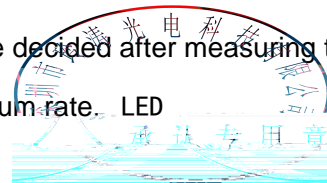


Fig. 1-5 The C.I.E. 1931 Chromaticity Diagram: (N&M)

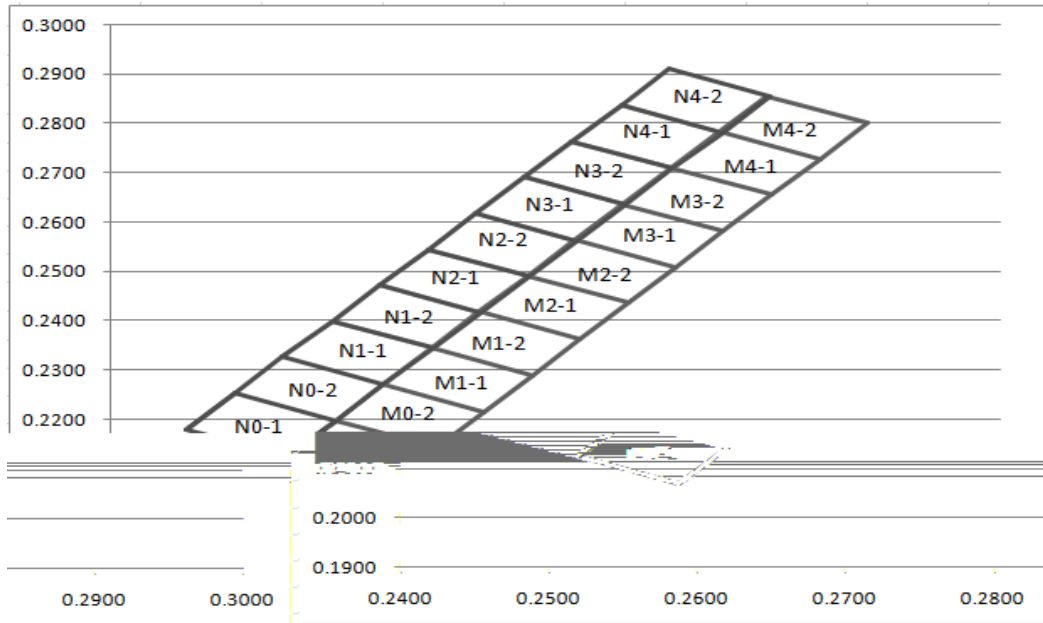


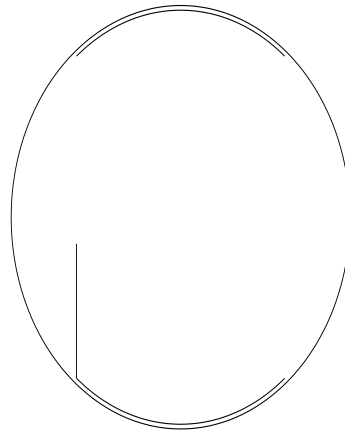
Table 1-6 Bin Range of Chromaticity Coordinates Block (IF=20mA ; Ta=25)

N0-1	0.2451	0.2180	N0-2	0.2484	0.2253	N1-1	0.2516	0.2326
	0.2484	0.2253		0.2516	0.2326		0.2549	0.2399
	0.2552	0.2198		0.2584	0.2271		0.2617	0.2344
	0.2519	0.2125		0.2552	0.2198		0.2584	0.2271
N1-2	0.2549	0.2399	N2-1	0.2581	0.2472	N2-2	0.2614	0.2545
	0.2581	0.2472		0.2614	0.2545		0.2646	0.2618
	0.2649	0.2417		0.2682	0.2490		0.2714	0.2563
	0.2617	0.2344		0.2649	0.2417		0.2682	0.2490
N3-1	0.2646	0.2618	N3-2	0.2679	0.2691	N4-1	0.2711	0.2764
	0.2679	0.2691		0.2711	0.2764		0.2744	0.2837
	0.2747	0.2636		0.2779	0.2709		0.2812	0.2782
	0.2714	0.2563		0.2747	0.2636		0.2779	0.2709
N4-2	0.2744	0.2837	M0-1	0.2519	0.2125	M0-2	0.2552	0.2198
	0.2776	0.2910		0.2552	0.2198		0.2584	0.2271
	0.2844	0.2855		0.2620	0.2143		0.2652	0.2216
	0.2812	0.2782		0.2587	0.2070		0.2620	0.2143
M1-1	0.2584	0.2271	M1-2	0.2616	0.2345	M2-1	0.2648	0.2418
	0.2616	0.2345		0.2648	0.2418		0.2681	0.2491
	0.2684	0.2290		0.2716	0.2363		0.2749	0.2436
	0.2652	0.2216		0.2684	0.2290		0.2716	0.2363
M2-2	0.2681	0.2491	M3-1	0.2713	0.2564	M3-2	0.2745	0.2637
	0.2713	0.2564		0.2745	0.2637		0.2777	0.2710
	0.2781	0.2509		0.2813	0.2582		0.2845	0.2655
	0.2749	0.2436		0.2781	0.2509		0.2813	0.2582

2. Packaging

2.1 Packaging Specification

Package:5000pcs/reel.



2.1.1 Carrier Tape Dimension

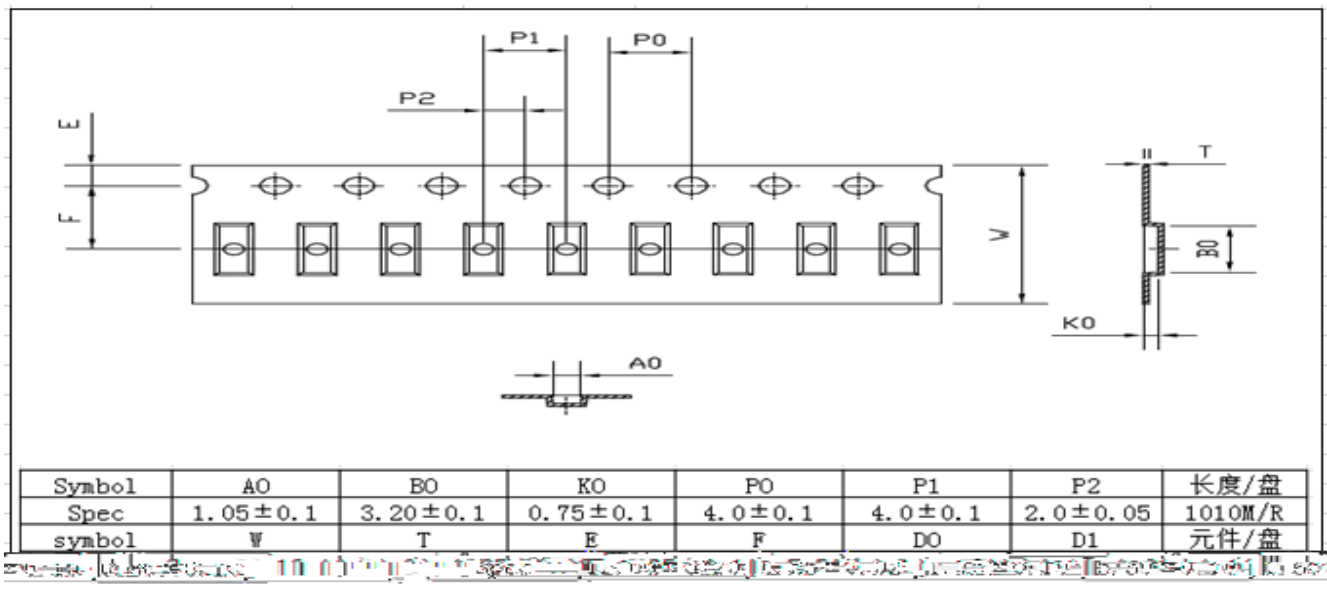
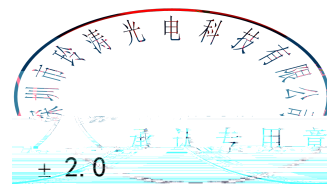


Fig.2-1 Carrier Tape Dimension

Notes

The tolerances unless mentioned ±2.0mm. Unit : mm



2.1.2 Label Form Specification

Table 2-3 Label Form Specification



PART NO.	Part Number
BIN CODE	Bin Code
IV	Luminous intensity
V _F	Forward Voltage
WL	Wavelength
QTY	Packing Quantity
DATE	Made Date
LOT NO	Lot Number 批次号

Table 2-2 Lable Map

2.2 Moisture Resistant Packing

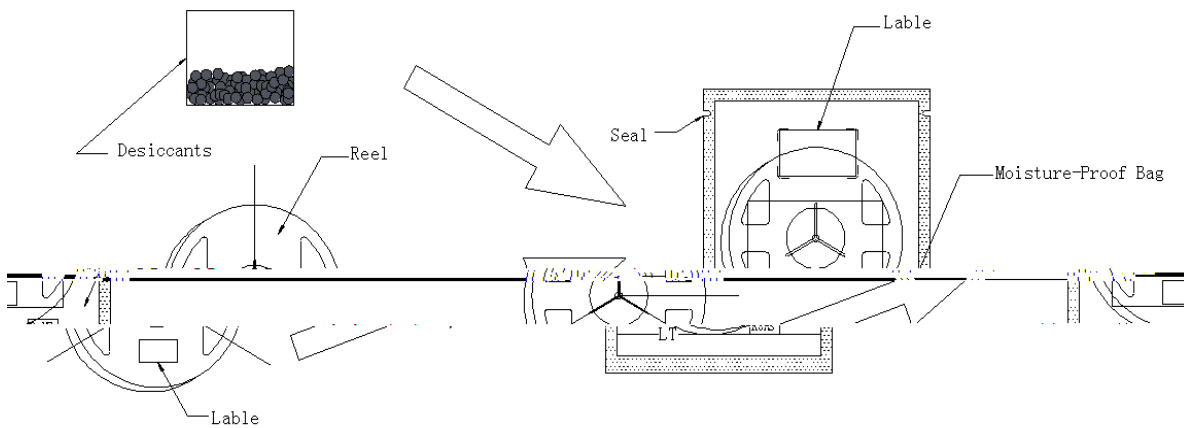


Fig.2-4 Moisture Resistant Packing

2.3 Cardboard Box

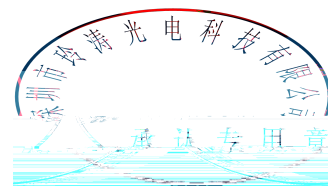
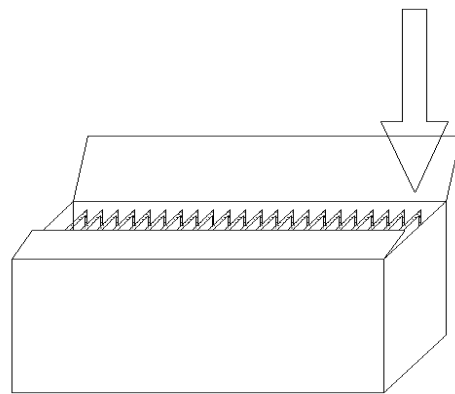


Fig.2-5 Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-6 Reliability Test Items And Conditions

TestItems	Test Condition	Time	Quantity	Ac/Re /
Reflow	Temp:260 max T=10 sec	---	20pcs.	0/1
Thermal Shock	-40 ~ 100 20min 10S 20min	100 cycle	20pcs.	0/1
High Temperature Storage	Temp:100	1000hrs.	20pcs.	0/1
Low Temperature Storage	Temp:-40	1000hrs.	20pcs.	0/1
Life Test	Ta=25 If=20mA	1000hrs.	20pcs.	0/1
High Temperature and Humidity storage	60 / 90%RH	1000hrs.	20pcs.	0/1
High Temperature and High Humidity Aging	60 / 90%RH If=15mA	500hrs.	20pcs	0/1

2.5 Criteria For Judging Damage

Table 2-7 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V _F	I _F =20mA		>U.S.L*)x1.1



Reverse Current	I_R	$V_R = 5V$	-	$>U.S.L^*) \times 2.0$
Luminous Flux		$I_F = 20mA$	$<L.S.L^*) \times 0.7$	-

Notes

1.U.S.L: Upper standard level L.S.L: Lower standard level

2.The above reliability tests is based on the verification of

Fig.3-2 SMT Reflow Soldering Instructions SMT

Average temperature rise speed	T_{smax} T_P	5 °C/	Max 5 °C/ s
Preheating: minimum temperature	(T_{smin})	160 °C	
Preheating: Max temperature	(T_{smax})	260 °C	
Preheating: Time	T_{smin} T_{smax}	60 - 120	60s-120s
Time limited to maintain high temperature: the temperature	(T_L)	217 °C	
Time limited to maintain high temperature: The Time	(t_L)	60	Max 60s
Peak /Classification of temperature:	/ (T_P)	260 °C	
Time limit classification of peak temperature time	t_p	10	Max 10s
(T_P) 5 °C actual peak temperature (TP)	Hold time within 5 ° C with the	30	Max 30s
Cooling speed		6 °C/	Max 6 °C/ s
25 °C	Needed time from 25 °C to T_p	8	Max 8 minutes

Notes

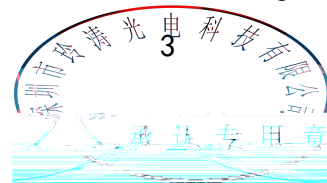
(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings , LED will be damaged. 24 LED

(2)Whensoldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

(1) When do soldering by hand, keep the temperature of iron below less 300°C less than 3 seconds , 300

(2) Soldering by hand should be done only one time.



3.1.2 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED

LED

3.1.3 Cautions

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED

LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board. LED PCB

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED LED 100PPM.

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

LED

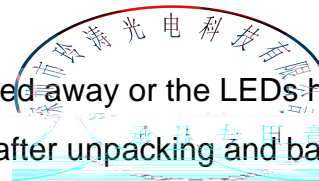
(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. LT suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED

Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage 储存	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	24hours 24
Baking		60± 5	-	24hours 24

(8) If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the



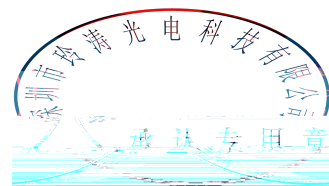
following condition (65±5) °C for above 24 hours.

60± 5

24

If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). LED



Version History/

Date	Revisor	Version	Verifier	Remarks
2019/10/18		E/0	刘娟	

